

Title (en)

Method for installing a floor covering on a floor

Title (de)

Verfahren zum Anbringen eines Bodenbelages auf einen Boden

Title (fr)

Procédé destiné à l'application d'un revêtement de sol sur un sol

Publication

EP 1953308 A1 20080806 (DE)

Application

EP 07101506 A 20070131

Priority

EP 07101506 A 20070131

Abstract (en)

The method involves introducing slits into an old floor covering (2), and introducing glue (5) e.g. SikaBond-T52 (RTM: wood flooring glue), into the slits. A new floor covering (6) e.g. carpet, is superimposed on the slits and bonded with floor (1) by an adhesive layer (3). The slits are applied on the floor, and a mat is arranged between the old and new floor coverings. The mat is applied before the glue is applied into the slits.

Abstract (de)

Bei einem Verfahren zum Anbringen eines Bodenbelages (6) auf einen Boden (1), werden Schlitze (4) in den alten Bodenbelag (2) eingebracht, Klebstoff (5) wird in die Schlitze (4) eingebracht, der neue Bodenbelag (6) aufgebracht und der neue Bodenbelage (6) mit dem Boden (1) verklebt.

IPC 8 full level

E04F 15/02 (2006.01)

CPC (source: EP US)

E04F 15/02 (2013.01 - EP US); **E04F 15/0215** (2013.01 - EP US); **E04F 15/20** (2013.01 - EP US)

Citation (search report)

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